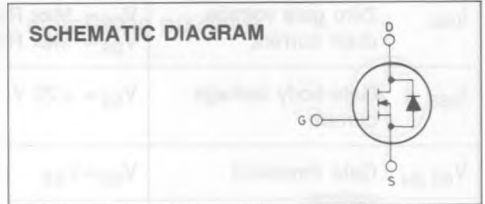


N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTOR IN DIE FORM

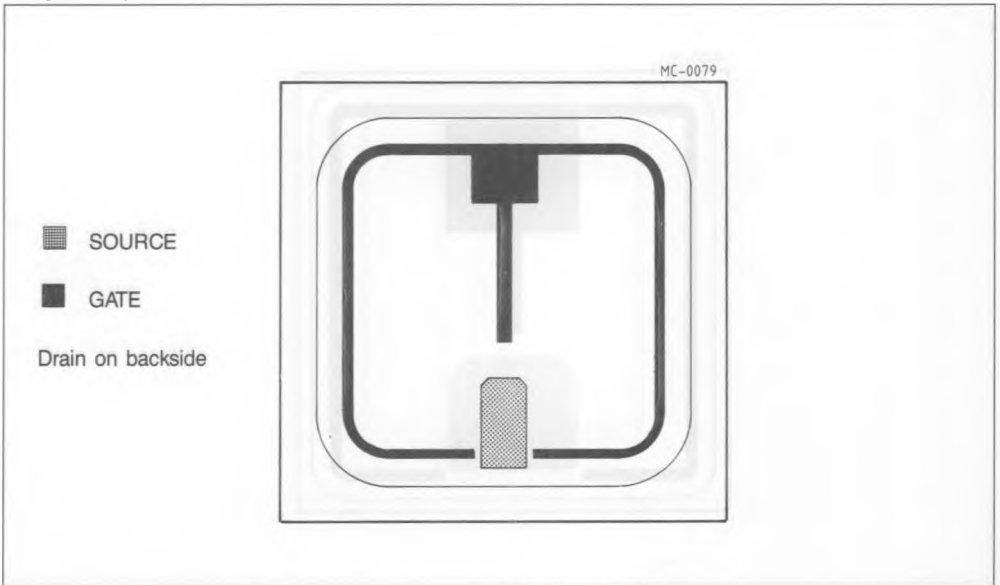
- DIE SIZE: 52 × 53 mils
- METALLIZATION:
 - Top Al
 - Back Au/Cr/Ni/Au
- BACKSIDE THICKNESS: 6100 Å
- DIE THICKNESS: 16 ± 2 mils
- PASSIVATION: P-Vapox
- BONDING PAD SIZE:
 - Source 10 × 5 mils
 - Gate 5 × 6 mils
- RECOMMENDED WIRE BONDING:
 - Source Au - max 2 mils
 - Gate Au - max 2 mils



V_{DSS}	$R_{DS(on)}$	I_D^*
400 V	20 Ω	0.6 A

N-channel enhancement mode POWER MOS field effect transistor. Easy drive and very fast switching times make this POWER MOS ideal for high speed switching applications.

Die geometry



* With R_{thj-c} max. 6.8°C/W

GUARANTEED PROBED ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ\text{C}$, Note 1)

Parameters		Test Conditions		Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}$	$V_{GS} = 0$	400			V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating} \times 0.8$	$T_j = 125^\circ\text{C}$			250 1000	μA μA
I_{GSS}	Gate-body leakage current	$V_{GS} = \pm 20 \text{ V}$				± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu\text{A}$	2		4	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}$	$I_D = 0.3 \text{ A}$			20	Ω

NOTES: 1 - Due to probe testing limitations dc parameters only are tested. They are measured using pulse techniques: pulse width $< 300 \mu\text{s}$, duty cycle $< 2\%$

2 - For detailed device characteristics please refer to the discrete device datasheet